REMARKS

An Office Action was mailed on December 26, 2002. Claims 1 – 3, 5 – 7, 12, 13 and 15 - 17 are pending in the present application. Claims 5 and 15 are allowed. Applicant amends claims 1 and 10, and cancels claims 3 and 13 without prejudice or disclaimer. No new matter is introduced.

ALLOWED CLAIMS

Applicant thanks the Examiner for indicating that claims 5 and 15 are allowed.

REJECTIONS UNDER 35 U.S.C. § 103

Claims 1 – 3, 6 – 7, 10, 12 – 13 and 16 - 17 are rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 5,346,518 to Baseman et al in view of U.S. Patent No. 5,772,738 to Muraoka. Claim 11 is rejected under 35 U.S.C. § 103(a) as being unpatentable over Baseman in view of Muraoka and U.S. Patent No. 6,093,947 to Hanafi et al. Applicant amends claims 1 and 10 to further clarify the nature of his invention, cancels claims 3 and 13 without prejudice or disclaimer, and respectfully traverses the above rejections.

Applicants' amended independent claims 1 and 10 respectively disclose an apparatus and method for semiconductor manufacture in which the a semiconductor substrate is stored in a stock/transfer vessel incorporating at least one adsorbent selected to be a material with a surface having an Si-F bond.

Baseman discloses a vapor drain system for a semiconductor manufacturing process. The system of Baseman includes a vapor removal element 30 including an absorber layer 60 including one of sputtered titanium and activated carbon. Unlike Applicant's claimed device, however, Baseman does not disclose or suggest an adsorbent including one of an ion-exchange resin and a material with a surface having a Si-F bond. Muraoka discloses a multi-function air filter and air-circulating clean unit. Muraoka acknowledges that air filtration can be performed using a absorber constituting an ion resin (see, e.g., column 1, lines 17 – 24 of Muraoka). However, each of Baseman, Muraoka and Hanafi fails to disclose or otherwise suggest Applicant's absorbent selected to be a material with a surface having an Si-F bond.

Accordingly, Applicants' respectfully submit independent claims 1 and 10 stand in condition for allowance. As claims 2 , 6 – 7, 11 – 12, and 16 – 17 depend from allowable claims 1 and 10, Applicant respectfully submits that claims 2 , 6 – 7, 11 – 12, and 16 – 17 stand in condition for allowance for at least this reason.

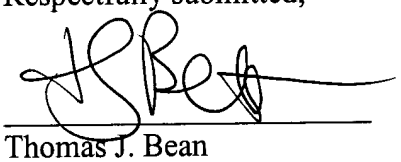
CONCLUSION

An earnest effort has been made to be fully responsive to the Examiner's objections. In view of the above amendments and remarks, it is believed that 1 – 2, 5 – 7, 10 – 12, 15 - 17, consisting of independent claims 1, 5, 10 and 15 and the claims dependent therefrom, are in condition for allowance. Passage of this case to allowance is earnestly solicited. However, if for any reason the Examiner should consider this application not to be in condition for allowance, he is respectfully requested to telephone the undersigned attorney at the number listed below prior to issuing a further Action.

Attached is a marked up version of the changes made to the specification and claims by the current amendment. The attached pages are captioned **"Version With Markings To Show Changes Made"**.

Any fee due with this paper may be charged on Deposit Account 50-1290.

Respectfully submitted,



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MARKED-UP COPY OF AMENDED APPLICATION – S/N 09/614,874

IN THE CLAIMS

Please cancel claims 3 and 13 without prejudice or disclaimer.

Please amend claims 1 and 10 as follows:

1. (Amended) A semiconductor substrate stock/transfer vessel, which is an openable/closeable sealed vessel used in a semiconductor device manufacturing process and adapted to store or transfer a semiconductor substrate,

wherein said vessel incorporates at least one adsorbent capable of adsorbing on organic substance, and said adsorbent is mounted detachably, and wherein said at least one adsorbent is [at least one of an ion-exchange resin and] a material with a surface having an Si-F bond.

10. (Amended) A method of manufacturing a semiconductor device wherein a semiconductor substrate is stored in a stock/transfer vessel incorporating at least one adsorbent capable of adsorbing an organic substance during an operation wait time between respective steps of manufacturing said semiconductor device, said adsorbent being mounted detachably, and wherein said at least one adsorbent is selected to be [at least one of an ion-exchange resin and] a material with a surface having an Si-F bond.